


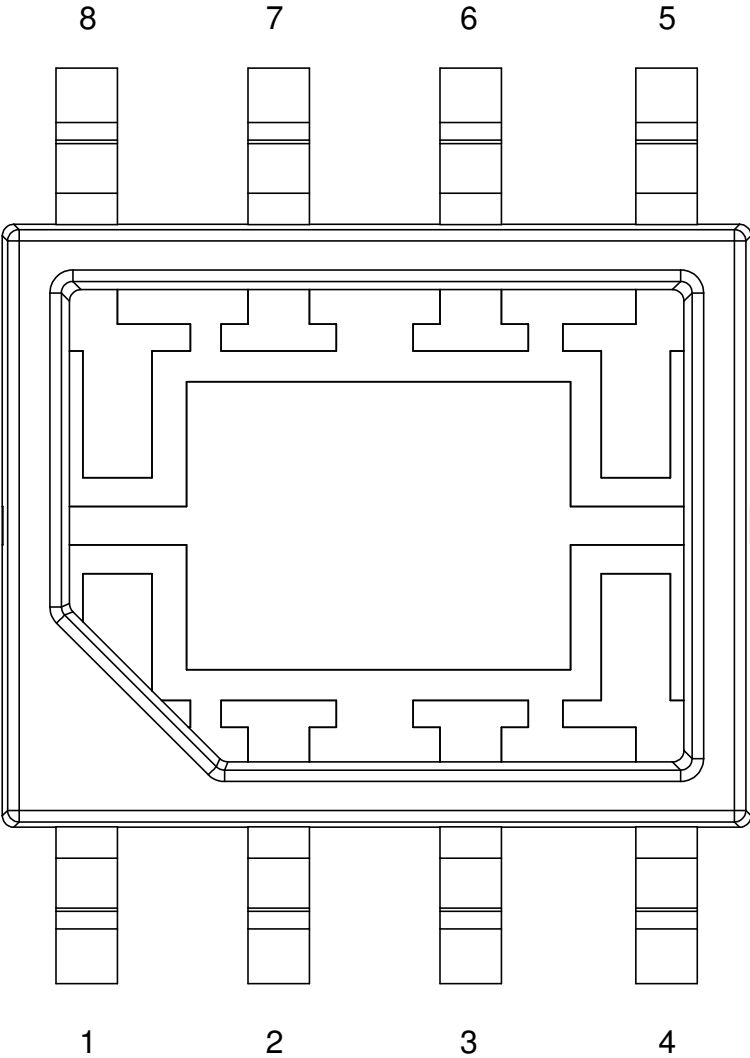
SECTION A-A


Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS: INCHES [MM].
- 2) PACKAGE CONFORMS TO JEDEC MS-012.
- 3) BODY: SEMICONDUCTOR GRADE MOLDING EPOXY.
- 4) LEAD FRAME: COPPER ALLOY A194 FULL HARD.
- 5) PLATING: NICKEL 100~300 MICRONS (2.5~7.6μM) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1.

APPROVALS		DATE				
DRAWN	J. Hines	1/30/2016				
ENG	M. Hart	1/30/2016	SCALE		SIZE	DRAWING NO.
MFG			10:1		A	120108
QA						REV
CUST						A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 4

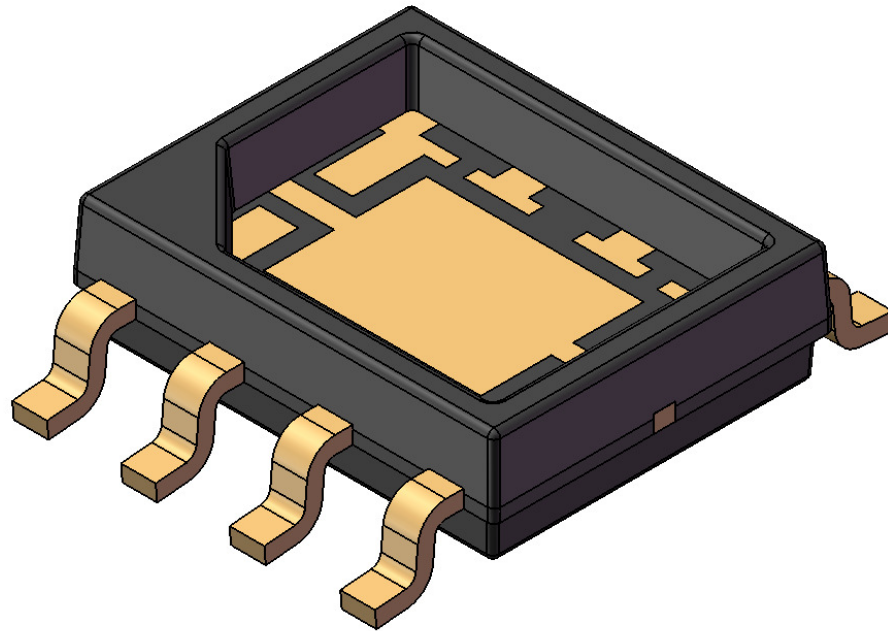
BOND DIAGRAM



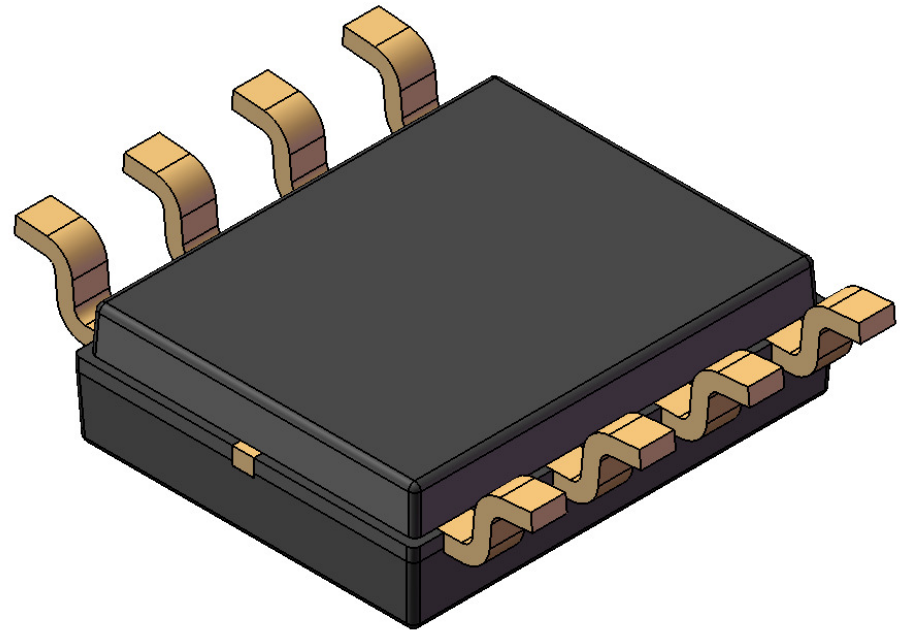
			
TITLE SOIC 8LD PITCH 1.27 MM OPEN CAVITY PACKAGE			
SCALE 20:1	SIZE A	DRAWING NO. 120108	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 4

MODEL

TOP



BOTTOM



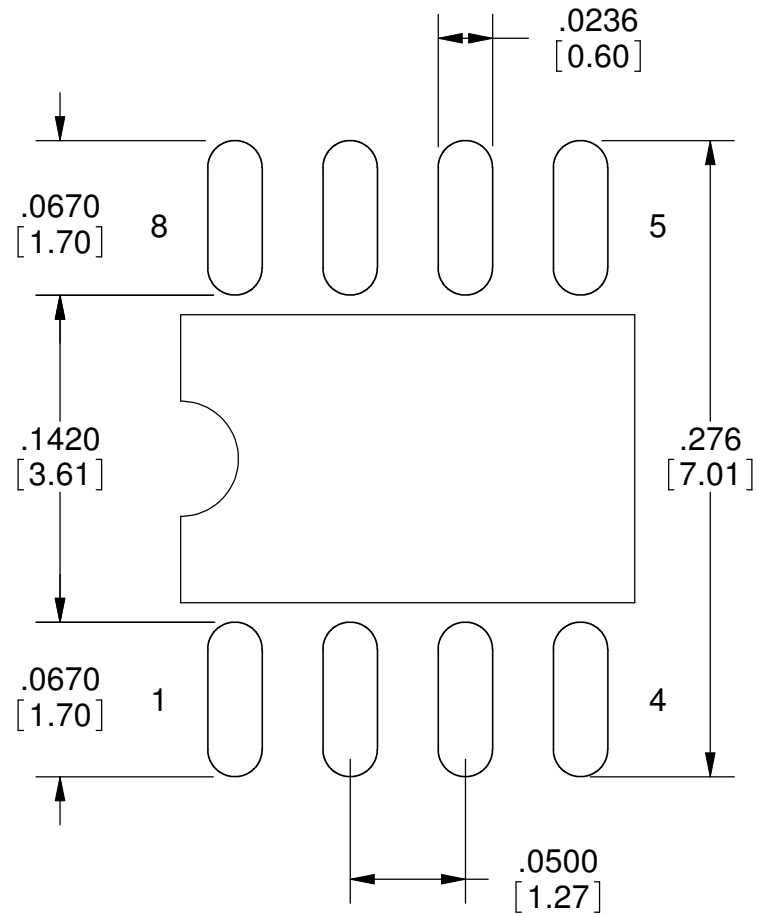
TITLE SOIC 8LD PITCH 1.27 MM
OPEN CAVITY PACKAGE

SCALE 16:1	SIZE A	DRAWING NO. 120108	REV A
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SHEET 3 OF 4

SUGGESTED PCB LAND PATTERN



Mirror
Semiconductor™

TITLE SOIC 8LD PITCH 1.27 MM
OPEN CAVITY PACKAGE

SCALE	SIZE	DRAWING NO.	REV
12:1	A	120108	A

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SHEET 4 OF 4